# **General Purpose Transistor**

## **PNP Silicon**

### Features

- Moisture Sensitivity Level: 1
- ESD Rating: Human Body Model: > 4000 V – Machine Model: > 400 V
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-25	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-25	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-4	Vdc
Collector Current–Continuous	Ι <sub>C</sub>	-200	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T <sub>A</sub> = 25°C Derate above 25°C	PD	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) @T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

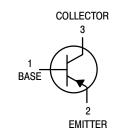
1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.

2. Alumina = 0.4  $\times$  0.3  $\times$  0.024 in. 99.5% alumina.



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http://onsemi.com





CASE 318 STYLE 6

## MARKING DIAGRAM



C3 = Device Code

= Pb–Free Package

(Note: Microdot may be in either location) \*Date Code orientation and/or overbar may vary depending upon manufacturing location.

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBT4126LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel

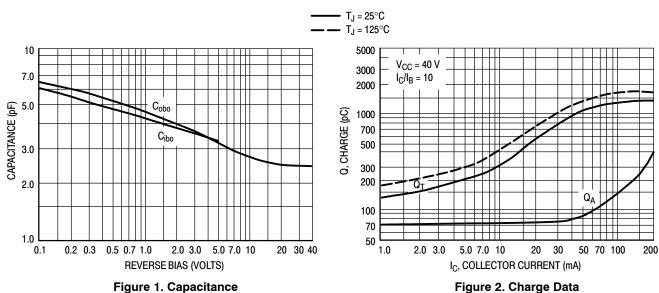
+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

M = Date Code\*

### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage (Note 3) $(I_{C} = -1.0 \text{ mAdc}, I_{B} = 0)$	V <sub>(BR)CEO</sub>	-25	_	Vdc
Collector-Base Breakdown Voltage $(I_{C} = -10 \ \mu Adc, I_{E} = 0)$	V <sub>(BR)CBO</sub>	-25	_	Vdc
Emitter–Base Breakdown Voltage ( $I_E = -10 \ \mu Adc, I_C = 0$ )	V <sub>(BR)EBO</sub>	-4	_	Vdc
Collector Cutoff Current ( $V_{CE} = -30$ Vdc, $V_{EB} = -3.0$ Vdc)	ICEX	_	-50	nAdc
ON CHARACTERISTICS (Note 3)			<b>L</b>	
DC Current Gain ( $I_C = -2.0 \text{ mAdc}$ , $V_{CE} = -1.0 \text{ Vdc}$ ) ( $I_C = -50 \text{ mAdc}$ , $V_{CE} = -1.0 \text{ Vdc}$ )	H <sub>FE</sub>	120 60	300 -	_
Collector – Emitter Saturation Voltage $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	V <sub>CE(sat)</sub>	_	-0.4	Vdc
Base – Emitter Saturation Voltage (I <sub>C</sub> = –50 mAdc, I <sub>B</sub> = –5.0 mAdc)	V <sub>BE(sat)</sub>	_	-0.95	Vdc
SMALL-SIGNAL CHARACTERISTICS				
Current – Gain – Bandwidth Product ( $I_C = -10$ mAdc, $V_{CE} = -20$ Vdc, f = 100 MHz)	f <sub>T</sub>	250	_	MHz
Output Capacitance (V <sub>CB</sub> = -5.0 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>obo</sub>	_	4.5	pF
Input Capacitance $(V_{EB} = -0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$	C <sub>ibo</sub>	_	10	pF
$ \begin{array}{l} \text{Small}-\text{Signal Current Gain} \\ (I_{C}=-2.0 \text{ mAdc}, \text{V}_{CE}=-10 \text{ Vdc}, \text{f}=1.0 \text{ kHz}) \\ (I_{C}=10 \text{ mAdc}, \text{V}_{CE}=20 \text{ Vdc}, \text{f}=100 \text{ MHz}) \end{array} $	h <sub>fe</sub>	120 2.5	480 -	-
Noise Figure (I <sub>C</sub> = –100 $\mu$ Adc, V <sub>CE</sub> = –5.0 Vdc, R <sub>S</sub> = 1.0 kΩ, f = 1.0 kHz)	NF	-	4.0	dB

3. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.



## **TYPICAL TRANSIENT CHARACTERISTICS**

### TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

(V<sub>CE</sub> = -5.0 Vdc, T<sub>A</sub> =  $25^{\circ}$ C, Bandwidth = 1.0 Hz)

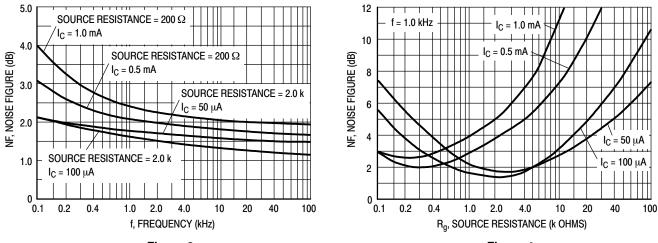
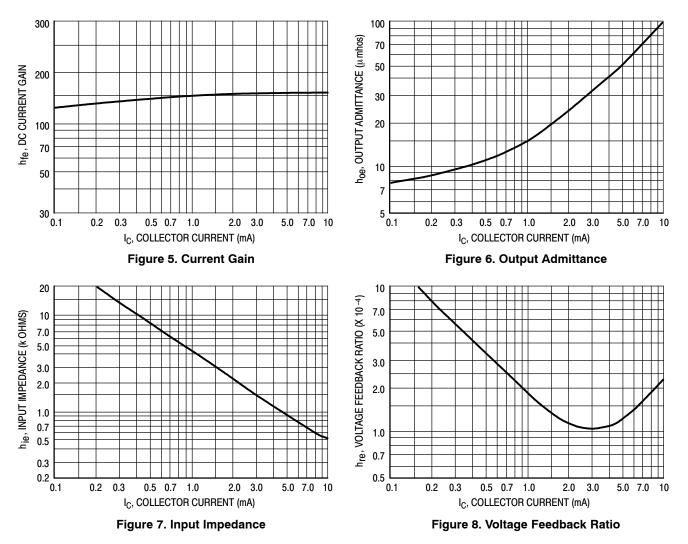


Figure 3.

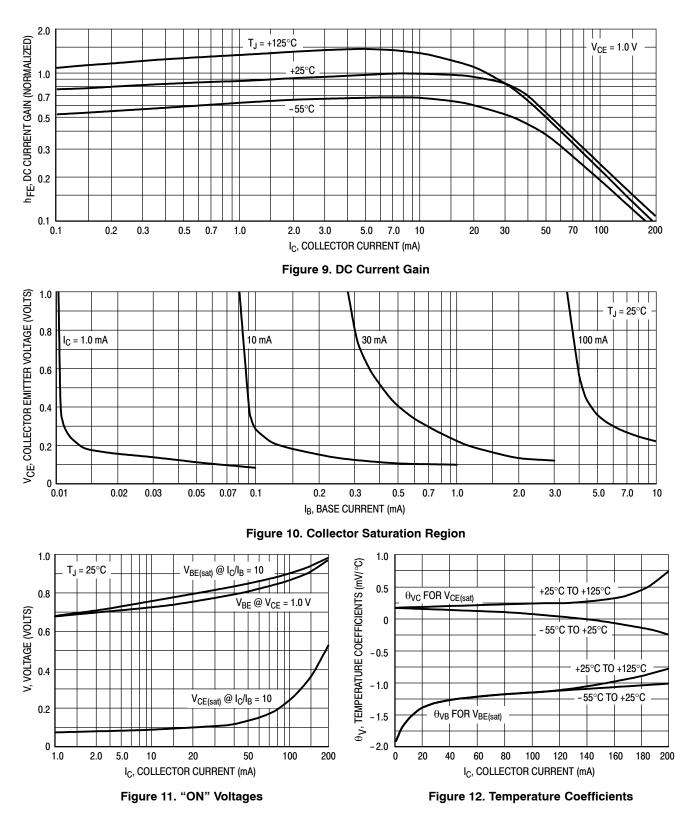
Figure 4.



(V<sub>CE</sub> = -10 Vdc, f = 1.0 kHz, T<sub>A</sub> =  $25^{\circ}$ C)

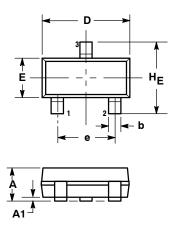


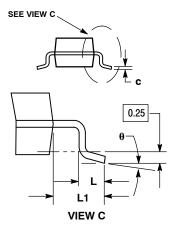
### **TYPICAL STATIC CHARACTERISTICS**



#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN** 





NOTES DIMENSIONING AND TOLERANCING PER 1.

DIMENSIONING AND TOLERANCING PER ANSI YI-45M, 1982.
CONTROLLING DIMENSION: INCH.
MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF DACE MATERIAL

BASE MATERIAL.

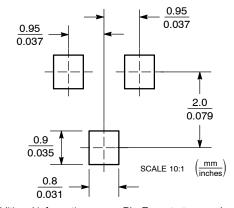
4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.89	1.00	1.11	0.035	0.040	0.044	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.37	0.44	0.50	0.015	0.018	0.020	
с	0.09	0.13	0.18	0.003	0.005	0.007	
D	2.80	2.90	3.04	0.110	0.114	0.120	
Е	1.20	1.30	1.40	0.047	0.051	0.055	
e	1.78	1.90	2.04	0.070	0.075	0.081	
L	0.10	0.20	0.30	0.004	0.008	0.012	
L1	0.35	0.54	0.69	0.014	0.021	0.029	
HE	2.10	2.40	2.64	0.083	0.094	0.104	

STYLE 6:

PIN 1. BASE 2. EMITTER З. COLLECTOR

**SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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